

July 2nd, 2004, Friday			
Session No 5: MEMS and Nano integration technology			
Chair	Dr.Hansjoerg Griese BeCAP, IZM, and Technical University of Berlin, Germany		
Co-Chair	Dr. Jianhua Zhang SMIT center, Shanghai University		
Venue	Room 1		
Time	No. of Paper	Title	Speaker
8.00-8.20	S5-1	Sustainable Development of Microelectronic Technology Processes Integration of EcoDesign	Dr. Hansjoerg Griese BeCAP, IZM, and Technical University of Berlin Germany
8.20-8.40	S5-2	Considerations for MEMS Packaging	Biye Wang San Jose State University, San Jose, California, USA
8.40-9.00	S5-3	Design of buried hinge based 3D torsional Micro mirrors	Sofiane Zairi School of Computing & Engineering, University of Huddersfield,UK
9.00-9.20	S5-4	A low cost bumping method for flip chip assembly and MEMS integration	J.H.Zhang School of Mechatronics Engineering and Automation, Shanghai University
9.20-9.40	S5-5	Integrated MEMS Technology	Cai ran College of Physical Electronics, University of Electronic Science and Technology of China
9.40-10.00	S5-6	A Micro- Semiconductor Tactile Sensor for the Automatic Obstacle-avoidance System of Endoscope	Shen Linyong School of Mechatronics Engineering and Automation, Shanghai University
10.00-10.30	Coffee Break and Exhibition		